

DESCRIPTION

The AM3415A uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as1.8V. This device is suitable for use as a load switch or in PWM applications .It is ESD protested.

The AM3415A is available in SOT-23 package.

ORDERING INFORMATION

Package Type	Part Number		
SOT-23	E3	AM3415AE3R	
501-23	ES	AM3415AE3VR	
Note	V: Halogen free Package		
Note	R: Tape & Reel		
AiT provides all RoHS products			
Suffix "V" means Halogen free Package			

FEATURES

● V_{DS} = -20V,I_D =-4A

 $R_{DS(ON)} < 60 m\Omega$ @ V_{GS} =-2.5V

 $R_{DS(ON)} < 47 m\Omega @ V_{GS} = -4.5 V$

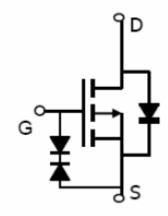
ESD Rating: 2500V HBM

- High Power and current handing capability
- Lead free product is acquired
- Surface mount package
- Available in SOT-23 Package

APPLICATION

- PWM application
- Load switch

TYPICAL APPLICATION

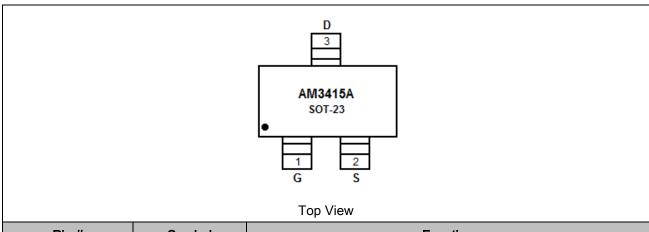


Schematic diagram

REV1.0 - JAN 2014 RELEASED - -1-

P-CHANNEL ENHANCEMENT MODE POWER MOSFET

PIN DESCRIPTION



Pin#	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain

REV1.0 - JAN 2014 RELEASED - - 2 -



ABSOLUTE MAXIMUM RATINGS

T_A=25°Cunless otherwise noted

V _{DS} , Drain-Source Voltage	-20V
V _{GS} , Gate-Source Voltage	±10V
I _D , Drain Current-Continuous	-4A
I _{DM} , Drain Current-Pulsed NOTE1	-30A
P _D , Maximum Power Dissipation	1.4W
T _J ,T _{STG} , Operating Junction and Storage Temperature Range	-55°C ∼ 150°C

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Repetitive Rating: Pulse width limited by maximum junction temperature.

THERMAL CHARACTERISTIC

Parameter	Symbol	MIN	MAX	Units
Thermal Resistance, Junction-to-Ambient NOTE2	R _{0JA}		89.3	°C/W

NOTE2: Surface Mounted on FR4 Board, t ≤ 10 sec.

REV1.0 - JAN 2014 RELEASED - - 3 -

ELECTRICAL CHARACTERISTICS

T_A=25°C, unless otherwise noted

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown	BV _{DSS}	V _{GS} =0V I _D =-250µA	-20	-	-	V
Zero Gate Voltage Drain	I _{DSS}	V _{DS} =-20V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	Igss	V _{GS} =±10V,V _{DS} =0V	-	-	±10	μΑ
On Characteristics NOTE3						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	V _{DS} =V _{GS} ,I _D =-250μA	-0.4	-0.65	-1.0	V
Drain-Source On-State	Dagger	V _{GS} =-4.5V, I _D =-4A	-	34.	47	mO.
Resistance	R _{DS(ON)}	V _{GS} =-2.5V, I _D =-4A	-	44	60	mΩ
Forward Transconductance	g fs	V _{DS} =-5V,I _D =-4A	8	-	-	S
Dynamic Characteristics NOTE4						
Input Capacitance	C_{lss}	- V _{DS} =-10V,V _{GS} =0V,	-	950	-	PF
Output Capacitance	C_{oss}		-	165	-	
Reverse Transfer Capacitance	C_{rss}	F=1.0MHz	-	120	-	
Switching Characteristics NOTE4						
Turn-on Delay Time	t _{D(ON)}		-	12	-	
Turn-on Rise Time	t R	V_{DD} =-10V, R _L =2. 5 Ω	-	10	-	nS
Turn-Off Delay Time	t _{D(OFF)}	V_{GS} =-4.5 V , R_{GEN} =3 Ω	-	19	-	110
Turn-Off Fall Time	t⊧		-	25	-	
Total Gate Charge	Q_{G}	- V _{DS} =-10V,I _D =-4A, - V _{GS} =-4.5V	-	12	-	
Gate-Source Charge	Q _{GS}		-	1.4	-	nC
Gate-Drain Charge	Q_{GD}		-	3.6	-	
Drain-Source Diode						
Diode Forward Voltage NOTE3	V_{SD}	V _{GS} =0V,I _S =-1A	-	-	-1.2	V
Diode Forward Current NOTE2	Is		-	-	-2.2	Α

NOTE2: Surface Mounted on FR4 Board, t ≤ 10 sec.

NOTE3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

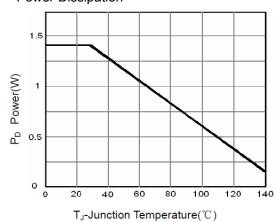
NOTE4: Guaranteed by design, not subject to production

REV1.0 - JAN 2014 RELEASED - - 4 -

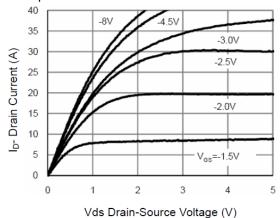


TYPICAL PERFORMANCE CHARACTERISTICS

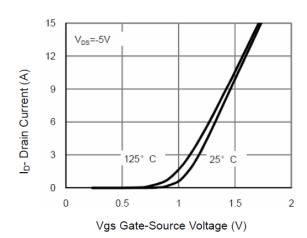
1. Power Dissipation



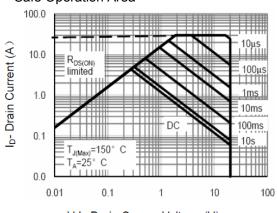
3. Output CHARACTERISTICS



5. Transfer Characteristics

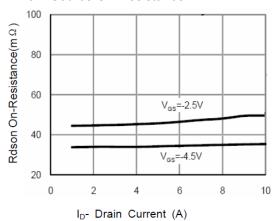


2. Safe Operation Area

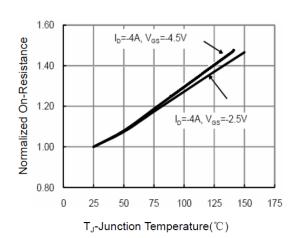


Vds Drain-Source Voltage (V)

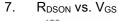
4. Drain-Source On-Resistance

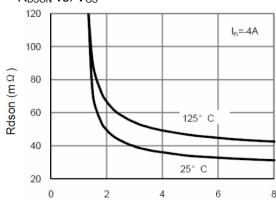


6. Drain-Source On-Resistance



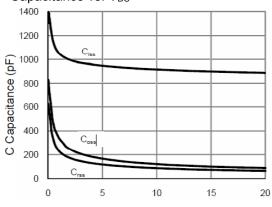
REV1.0 - JAN 2014 RELEASED - - 5 -





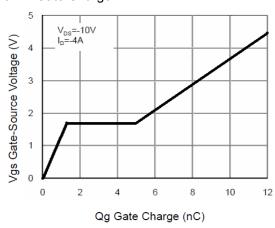
Vgs Gate-Source Voltage (V)

8. Capacitance vs. V_{DS}

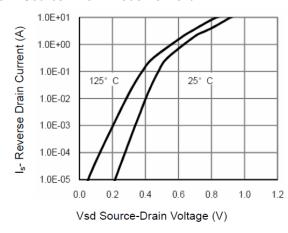


Vds Drain-Source Voltage (V)

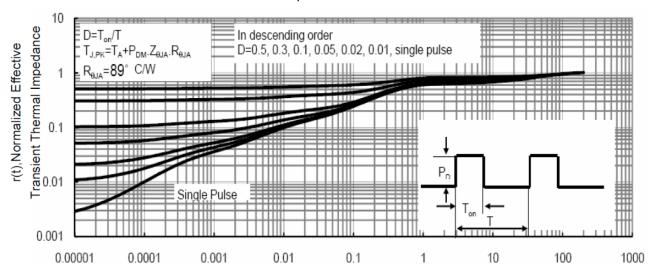
9. Gate Charge



10. Source- Drain Diode Forward



11. Normalized Maximum Transient Thermal Impedance



REV1.0 - JAN 2014 RELEASED - - 6 -

DETAILED INFORMATION

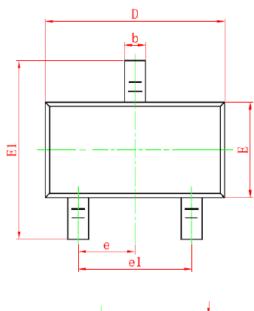
Switching Test Circuit **Switching Waveforms** Vdd t_{d(on)} $\mathbf{t}_{d(off)}$ RI Vin Vout 90% V_{OUT} **INVERTED** Rgen 90% \mathbf{V}_{IN} 50% **PULSE WIDTH**

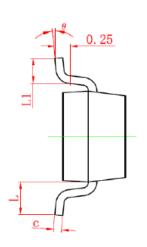
REV1.0 - JAN 2014 RELEASED - - 7

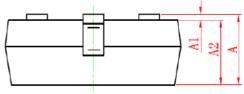


PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)







SYMBOL	MIN	MAX	
Α	0.900	1.150	
A1	0.000	0.100	
A2	0.900	1.050	
b	0.300	0.500	
С	0.080	0.150	
D	2.800	3.000	
Е	1.200	1.400	
E1	2.250	2.550	
е	0.950(BSC)		
e1	1.800	2.000	
L	0.300	0.500	
θ	0°	8°	

REV1.0 - JAN 2014 RELEASED - - 8 -



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REV1.0 - JAN 2014 RELEASED - - 9 -